

“HALF-BRIDGE” IGBT MODULE

Feature

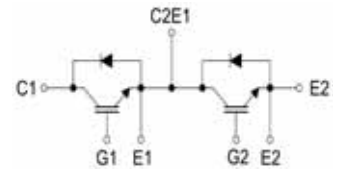
- Smart field stopper + Trench design technology
- Low $V_{CE(sat)}$
- Low Turn-off losses
- Short tail current for over 20KHz

Applications

- Motor controls
- VVVF inverters
- Inverter-type welding MC over 18KHZ
- SMPS, Electrolysis
- UPS/EPS, Robotics



Package : V3



$V_{CES} = 600V$

$I_c = 300A$

$V_{CE(ON)}$ typ. = 1.5V
@ $I_c = 300A$

Absolute Maximum Ratings @ $T_j = 25^\circ C$ (Per Leg)

Symbol	Parameter	Condition	Ratings	Unit
V_{CES}	Collector-to-Emitter Voltage	$T_c = 25^\circ C$	600	V
V_{GE}	Gate emitter voltage		± 20	V
I_c	Continuous Collector Current	$T_c = 80^\circ C (25^\circ C)$	300 (430)	A
I_{CP}	Pulsed collector current	$T_c = 25^\circ C$	600	A
I_F	Diode Continuous Forward Current	$T_c = 80^\circ C (25^\circ C)$	300 (430)	A
I_{FM}	Diode Maximum Forward Current	$T_c = 25^\circ C$	600	A
t_p	Short circuit test, $V_{GE} = 15V$, $V_{CC} = 360V$	$T_c = 150^\circ C (25^\circ C)$	6 (8)	μs
V_{iso}	Isolation Voltage test	AC @ 1 minute	2500	V
Weight	Weight of Module		360	g
T_j	Junction Temperature		-40 ~ 150	$^\circ C$
T_{stg}	Storage Temperature		-40 ~ 125	$^\circ C$
Md	Mounting torque with screw : M6		4.0	N.m

Static Characteristics @ $T_j = 25^\circ C$ (unless otherwise specified)

Parameters		Min	Typ	Max	Unit	Test conditions
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage		1.50	1.95	V	$I_c = 300A$, $V_{GE} = 15V$
$V_{GE(th)}$	Gate Threshold Voltage		5.8	6.5		$V_{CE} = V_{GE}$, $I_c = 8mA$
I_{CES}	Zero Gate Voltage Collector Current	—	—	5.0	mA	$V_{GE} = 0V$, $V_{CE} = 600V$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	400	nA	$V_{CE} = 0V$, $V_{GE} = 20V$
V_F	Forward voltage drop		1.6	1.9	V	$I_F = 300A$
R_{GINT}	Integrated gate resistor	—	1	—	Ω	

Electrical Characteristic Values (IGBT / DIODE) @ $T_j = 25^\circ\text{C}$ (unless otherwise specified)

Parameters		Min	Typ	Max	Unit	Test conditions
Ciss	Input capacitance	—	18480	—	pF	V _{CE} = 25V, V _{GE} = 0V f = 1 MHz
Coss	Output capacitance	—	1152	—		
Crss	Reverse transfer capacitance	—	548	—		
td(on)	Turn-on delay time	—	115	—	ns	Inductive Switching (125) V _{CC} = 300V I _C = 300A, V _{GE} = ±15V R _G = 3.3Ω
tr	Rise time	—	45	—		
td(off)	Turn-off delay time	—	200	—		
tf	Fall time	—	45	—		
VBR	Cathode-Anode breakdown Voltage	600	—	—	V	
IRM	Maximum Reverse Leakage Current	—	—	350	μA	V _R = 600V
trr	Reverse Recovery Time	—	120	—	ns	I _F = 300A, V _R = 300V di / dt = 3100A / μs
Qrr	Reverse Recovery Charge	—	13.5	—	μC	

Thermal Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
RθJC	Junction-to-Case (IGBT Part, Per 1/2 Module)	-	-	0.13	/W
RθJC	Junction-to-Case (Diode Part, Per 1/2 Module)	-	-	0.21	
RθCS	Case-to-Heat Sink (Conductive grease applied)	-	0.03	-	

Fig.1 Output characteristic (typical)

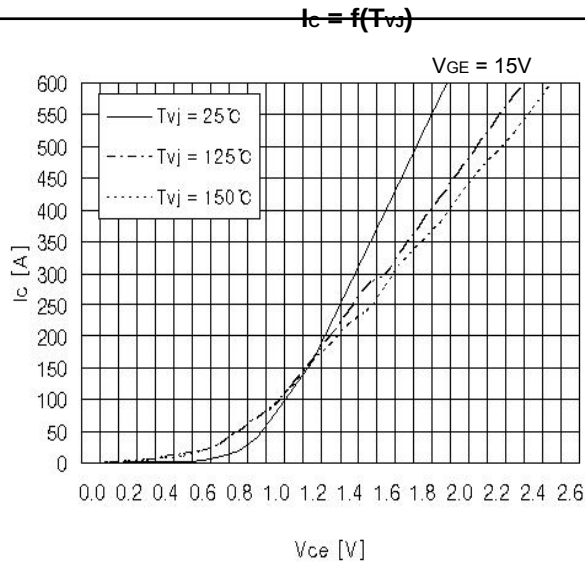


Fig.2 Output characteristic (typical)

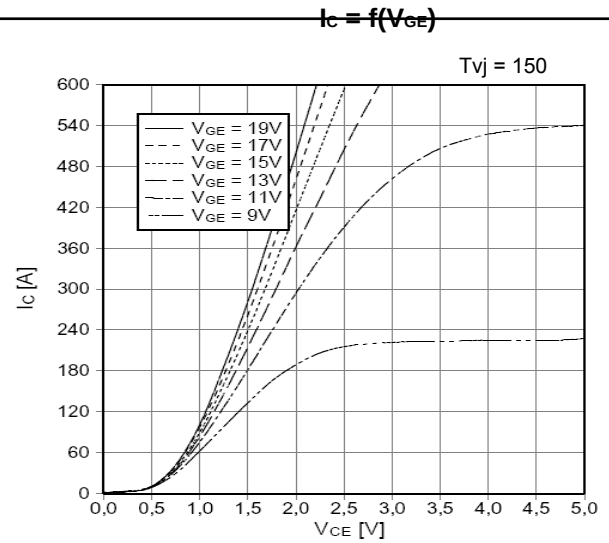


Fig.3 Transfer characteristic (typical)

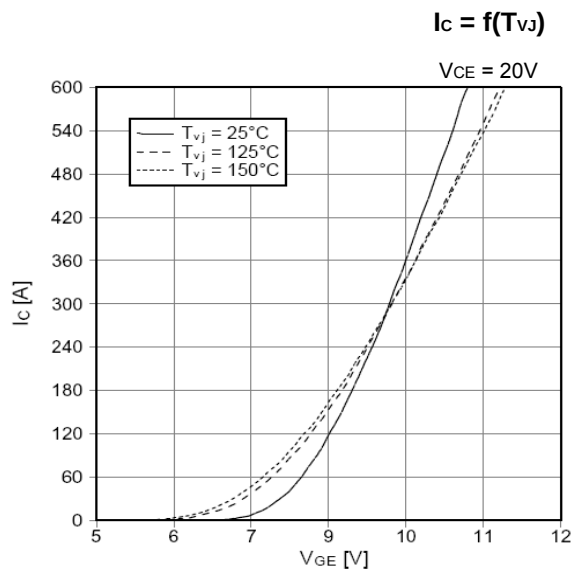


Fig.4 Reverse bias RBSOA

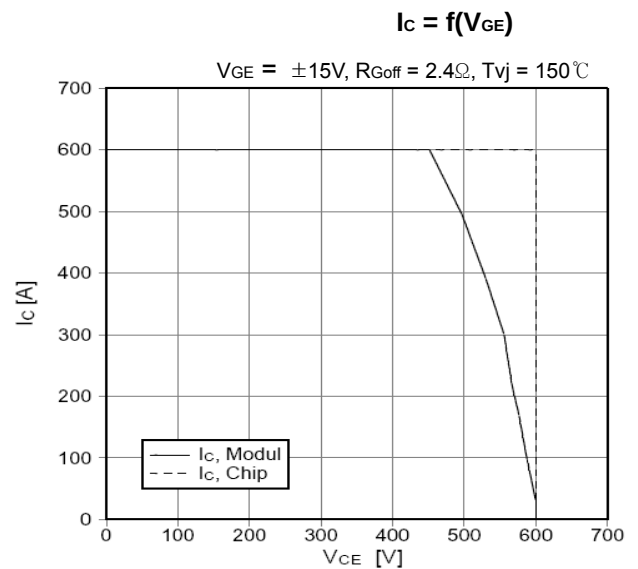
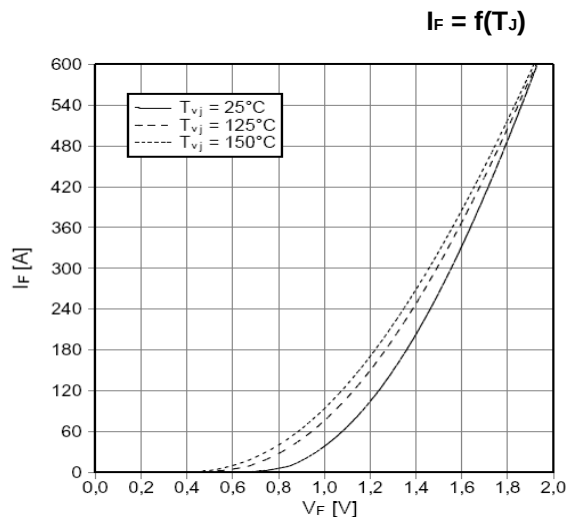
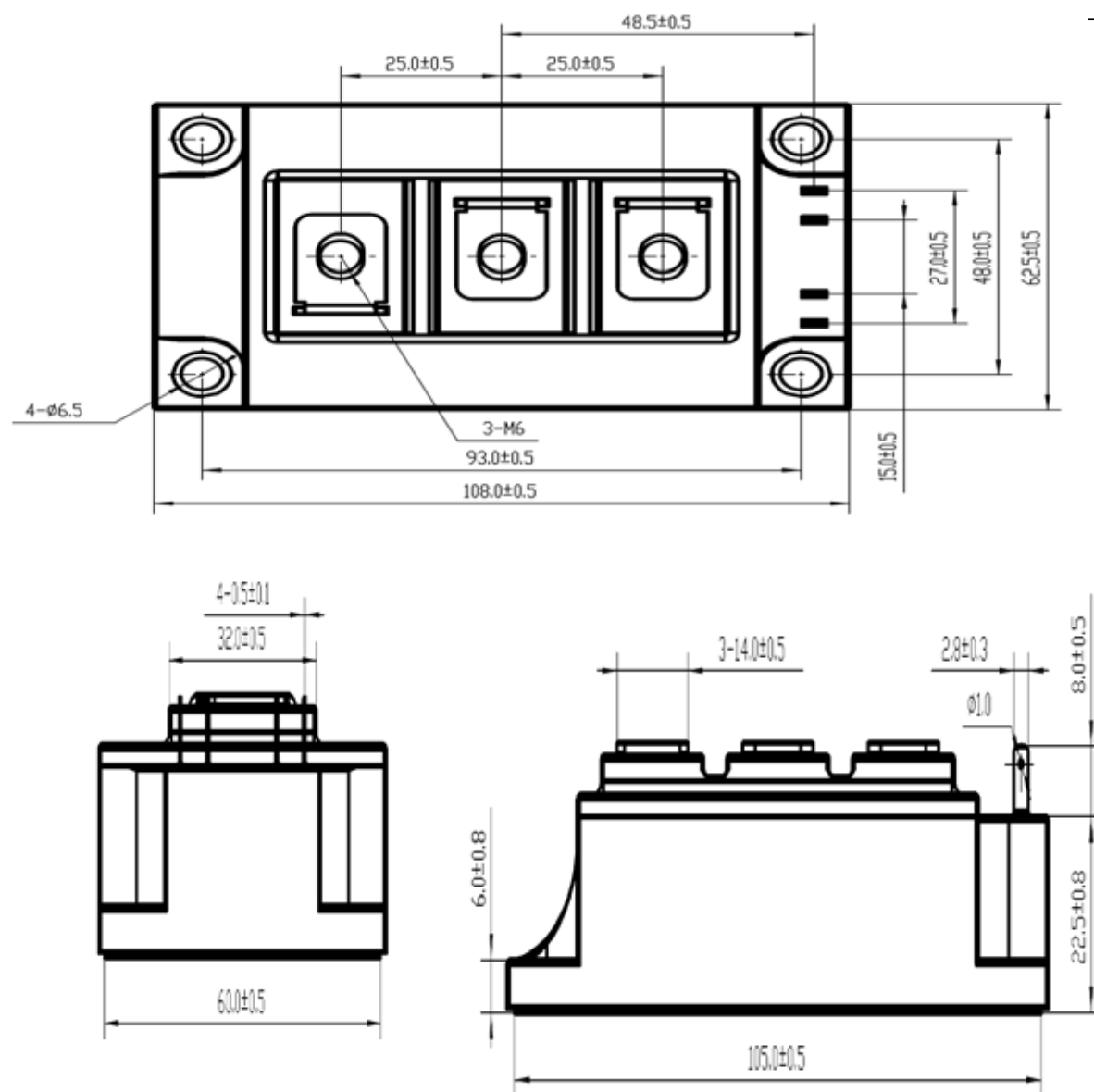


Fig.5 Forward characteristic of diode (typical)



Package Outline (dimensions in mm)



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